

SPI-335-34

Ultraminiature photoreflector (single-transistor type)

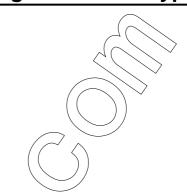
Features

• Infrared LED plus Phototransistor (single)

• DIP type

• Compact type : 3.4 (L) X 2.7 (W) X 1.5 (H) mm

Visible light cut type Lead length : (L=3.5mm)



Absolute Maximum Ratings at Ta=25°C, 65%RH

Parameter		Symbol /	Rating	Unit
Input LED	Forward Current	I _F //	50	mA
	Reverse Voltage	V_R	5	V
	Power Dissipation	PD	70	mW
Output Phototransistor	Collector-Emitter Voltage	YCEO	20	V
	Emitter-Collector Voltage	(VECO)	5	V
	Collector Curren	$\downarrow \downarrow $	20	mA
	Power Dissipation	P _C	70	mW
Operating Temperature		Topr	-20 to +80	°C
Storage Temperature		Tstg	-40 to +100	°C
Soldering Temperature *1		Tsol	260	°C

^{*1} Soldering conditions: time: max. 3sec; clearance: min. 1 mm from lower case edge.

Electro-Optical Characteristics at Ta=25 C, 65%RH

Parameter		Symbol	Condition	Min.	Тур.	Max.	Unit
Innut	Forward Voltage	V_{F}	I _F =10mA	1.0	1.2	1.6	V
Input	Reverse Current	IR>	V _R =5V	-	-	10	μΑ
Output	Output Dark Current		I _F =0mA, V _{CE} =10V	-	10	200	nA
Coupled	Collector Output Current	$\searrow_{\mathrm{I_C}}$	I _F =4mA,V _{CE} =5V*1	33	-	180	μΑ
	Leakage Current	I _{LEAK}	I _F =10mA,V _{CE} =5V*2	-	-	1	μΑ
	Collector Emitter Saturation Voltage	V _{CE} (sat)	I _F =10mA, I _C =50μA	-	-	0.5	V
	Rise Time	tr	V_{CC} =5V, R_L =100 Ω	-	5	-	μs
	Fall Time	tf	I _C =1mA	-	5	-	μs

^{*1} Location of reflector is show in Fig. 1.

^{*3} Table of Classification of Collector Output

Class	E	F	G	Н	
Ic (μA)	180 to 110	140 to 80	100 to 50	65 to 33	
Marking color	Orange	Green	White	Silver	

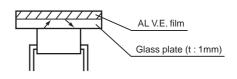


Fig. 1 Location of Reflector

^{*2} No reflector

Package dimensions and Pin connection

As stated in the sttached paper. (No.6029 5/6)

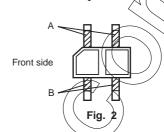
Rank marking of collector output

The bottom of the package is colored following the table of classification of collector output.

Lot marking

Color division shall be done as shown in the drawing. (Fig. 2)

Year of even number : Front side Year of odd number : Back side

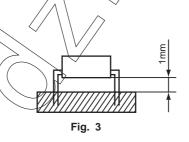


Color	Black	Blue	Red	Green	Orange	Brown
Part 'A'	January	February	March	April	May	June
Part 'B'	July	August	September	October	November/	December

Soldering conditions

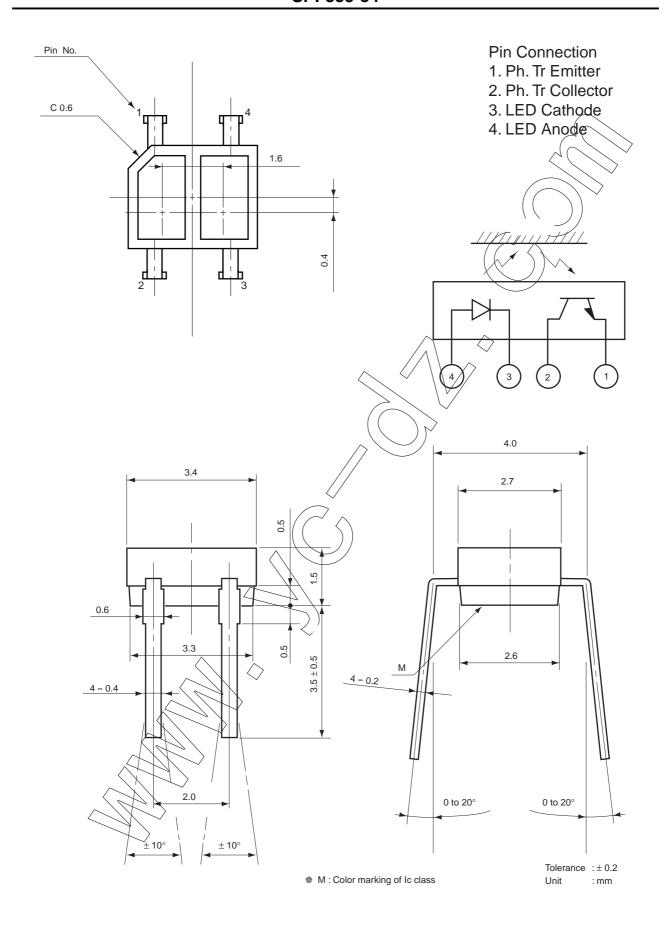
(1) Temperature : Max. 260°C (2) Time : Max. 3sec

(3) Clearance : Min. 1mm from the case edge. (Fig. 3)



A PRECAUTIONS

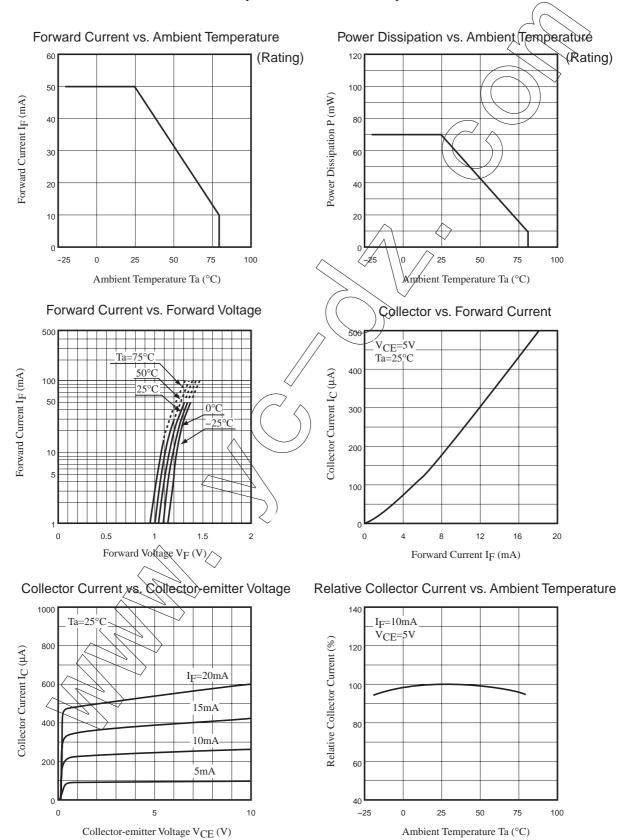
- (1) Bending a lead should avoid. However, when bending is necessary, take care the next items.
 - ① Bending a lead must be done before soldering.
 - 2 Bending a lead must be done in the states of fixing leads and no stress for the regin part. Because it is possible that stress for the regin part cause troubles such as gold wire breaking and so on.
 - 3 A lead must be bend at intervals of 2mm from the case edge.
 - 4 Do not bend the same position of leads more than twice.
- (2) The hole pitch of a circuit board must fit to the lead pitch.
- (3) Take core the following when soldering.
 - ① Do not heat a product under any stress (a twist and so on) to leads.
 - 2 Do not heat a product in the states of operating force to the regin part.
- (4) Use the flux which contain no chlorine, have no corrosion and do not need washing.
- (5) Be careful that flux or other chemicals do not attach to the luminous surface and passive surface.



Typical Characteristics

▲ CAUTION

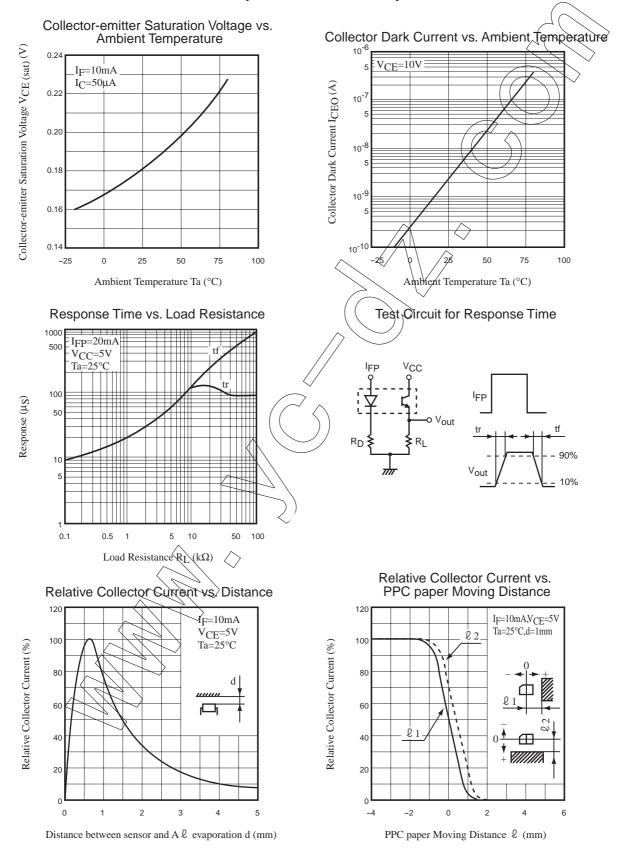
These numerical value show the electrical and optical characteristics of this product, and not assure this contents.

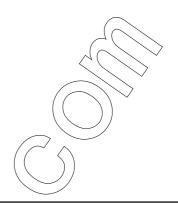


Typical Characteristics

A CAUTION

These numerical value show the electrical and optical characteristics of this product, and not assure this contents.







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Precautionary instructions in handling gallium arsenic products

Special presautions must be taken in handling this product because it contains, gallium arsenic, which is designated as a toxic substance by law. Be sure to adhere strictly to all applicable laws and regulations enacted for this substance, particularly when it comes to disposal.

Manufactured by; Tottori SANYO Electric Co., Ltd.

LED Division

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